

AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior versions and listings of Claims in the Application:

Listing of Claims:

Claim 1 (Currently Amended): An improved structure of gold fingers, built in a stacked-chip packaging structure, and the stacked-chip packaging structure, comprising includes

a packaging substrate;

a plurality of ~~stacked~~ chips stacked on said packaging substrate, and each said chip has a plurality of wires that is connected to including at least one chip wire; and

a plurality of gold finger sets positioned on said packaging substrate, wherein each said gold finger set ~~has~~ includes a plurality of gold finger units ~~that are~~ electrically connected to one another by a conductive material and positionally separated one from another by a solder resist structure extending above said conductive material, and wherein said at least one chip wires of said plurality of the stacked chips to each wire that can be connected to one another on each chip is are connected to the said gold finger ~~unit~~ units of the same gold finger set, each said at least one chip wire being connected to a distinct gold finger unit.

Claim 2 (Canceled).

Claim 3 (Currently Amended): The improved structure of gold fingers as claimed in claim 2 1, wherein the number of ~~the~~ said gold finger units in each said gold finger set is equal or exceeds ~~is not less than~~ the number of ~~the~~ said stacked chips.

Claim 4 (Canceled).

Claim 5 (Currently Amended): The improved structure of gold fingers as claimed in claim 1, wherein ~~between each gold finger unit, there is~~ said conductive material includes at least one connecting wire extending between respective ~~to connect the~~ gold finger ~~unit~~ units ~~so as to form electrical connection~~ therebetween.

Claim 6 (Currently Amended): The improved structure of gold fingers as claimed in claim 4-5, wherein a said solder resister ~~layer~~ structure covers ~~the~~ said at least one connecting wire.

Claim 7 (Currently Amended): The improved structure of gold fingers as claimed in claim 1, wherein ~~the~~ said gold finger set ~~can be~~ is a complete gold finger, wherein said conductive material is a material of said complete gold finger, and ~~at least one wherein~~ said solder resist ~~layer~~ structure covers a part of the surface of the complete gold finger so as to divide it the latter into a plurality of said gold finger units.